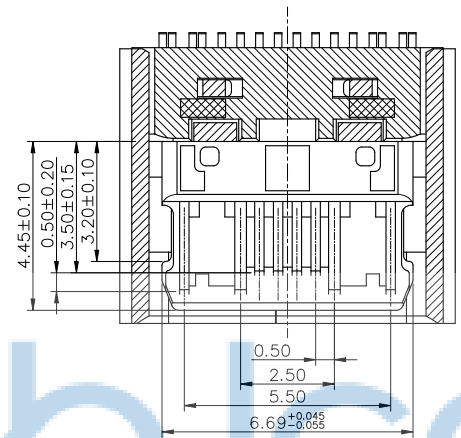
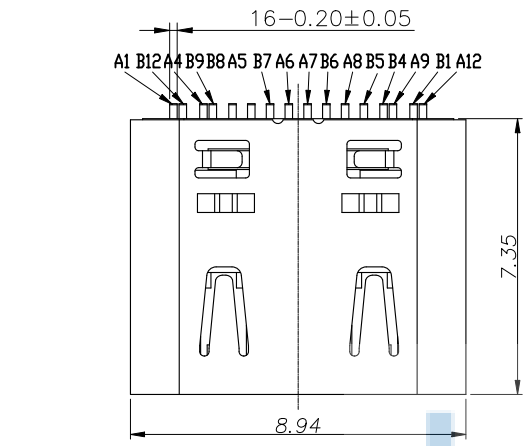


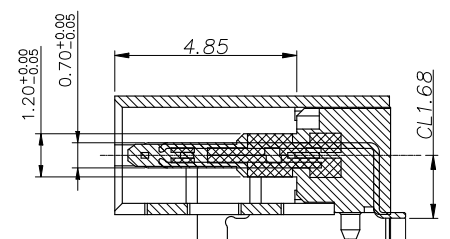
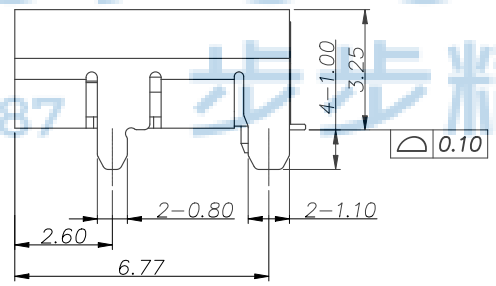
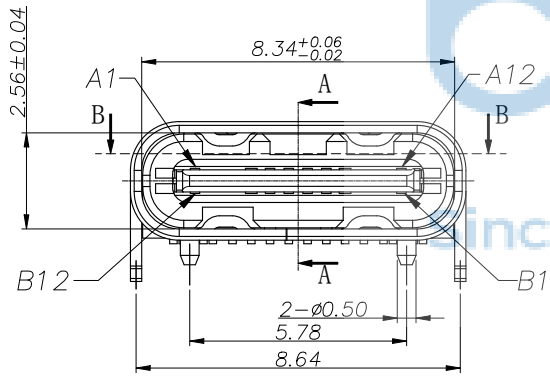
REV.	ECN NO.	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP

NOTE:

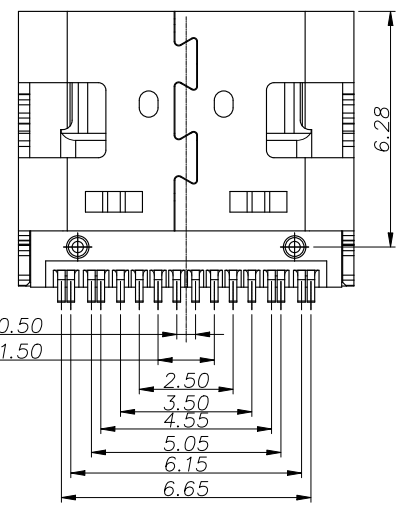
- MATERIAL SPECIFICATION:
 - HOUSING: HIGH TEMPERATURE RESISTANT PLASTIC, UL94 V-0.
 - CONTACTS: COPPER ALLOY
 - MID PLATE: STAINLESS STEEL
- PLATING SPECIFICATION:
 - CONTACTS:
 - Ni 50u" MIN. UNDER PLATED OVER ALL.
 - Au 30u" PLATED ON THE FUNCTIONAL AREA OF CONTACT. (GOLD PLATING THICKNESS FOLLOW)
 - GOLD FLASH PLATING ON SOLDER AREA
 - FRONT SHELL:
 - Ni 30u" MIN. UNDER PLATED OVER ALL.
- MECHANICAL PERFORMANCE,
 - INSERTION FORCE: 0.5~2.0kgf.
 - REMOVAL FORCE: 0.8kgf~2.0kgf.
 - DURABILITY: 10000 CYCLES.
- ELECTRICAL PERFORMANCE,
 - CURRENT RATING: 5A
VOLTAGE RATING: 20V
 - INSULATION RESISTANCE: 100MΩ MIN
 - DIELECTRIC WITHSTAND VOLTAGE, AC 100V FOR 1 MINUTE.
 - LOW CONTACT RESISTANCE: INITIAL 40MΩ
AFTER 50MΩ
- ENVIRONMENTAL PERFORMANCE:
 - OPERATING TEMPERATURE: -30°C~+80°C.
- IR REFLOW:
 - THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260°C.



SECTION B-B
SCALE 1:1



SECTION A-A
SCALE 1:1



4	SHELL	SUS304 T=0.30MM	Ni 30u"MIN	1PCS
3	SHIELDING PLATE	SUS301 T=0.15MM	N/A	1PCS
2	CONTACT	C2680 T=0.15MM	Mating area 30u"Au Solder Tails: G/F Underplate: 50u"Min Ni overall	2SET
1	INSERT MOLDING	LCP UL94V-0	BLACK	1PCS
NO.	DESCRIPTION	MATERIAL	REMARKS	

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深圳市步步精科技有限公司

NAME: TYPE-C 16P 母座 SMT 镀金30U 板上四脚插 带柱
外壳四脚点带弹不折弯凸包印子 L=7.35 CH=1.68 编带

APPD. JM_Zheng

CHKD. LYX

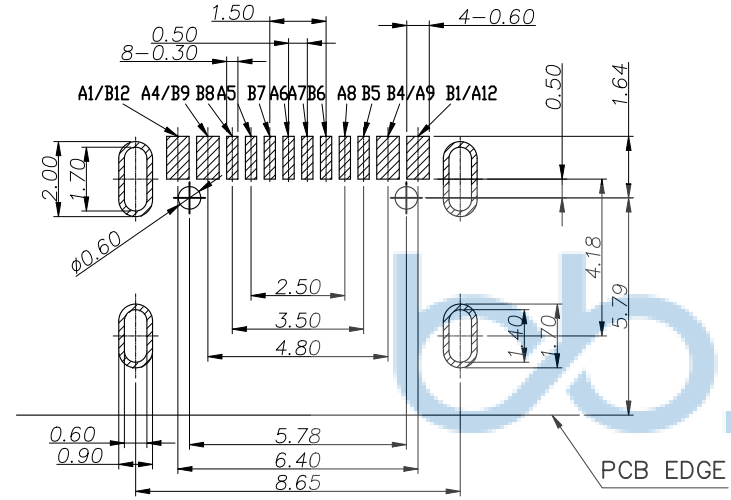
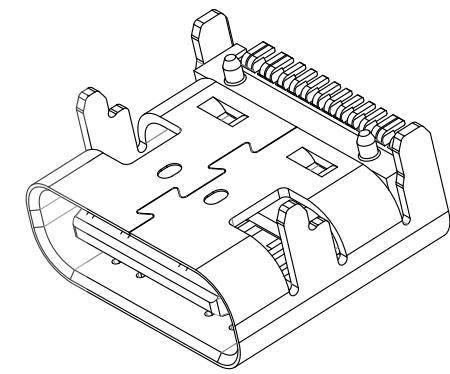
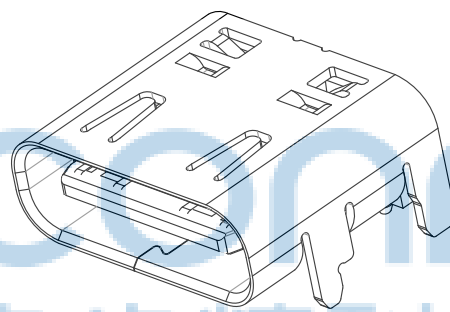
DR. TSP

PJ. NO.: 126-273-160001-V2G

SIZE: A4 DRW NO.:

FINISH: SEE NOTES MAT'L.: SEE NOTES

SCALE: N/A REV.: A0 UNIT: mm PAGE: 1/3



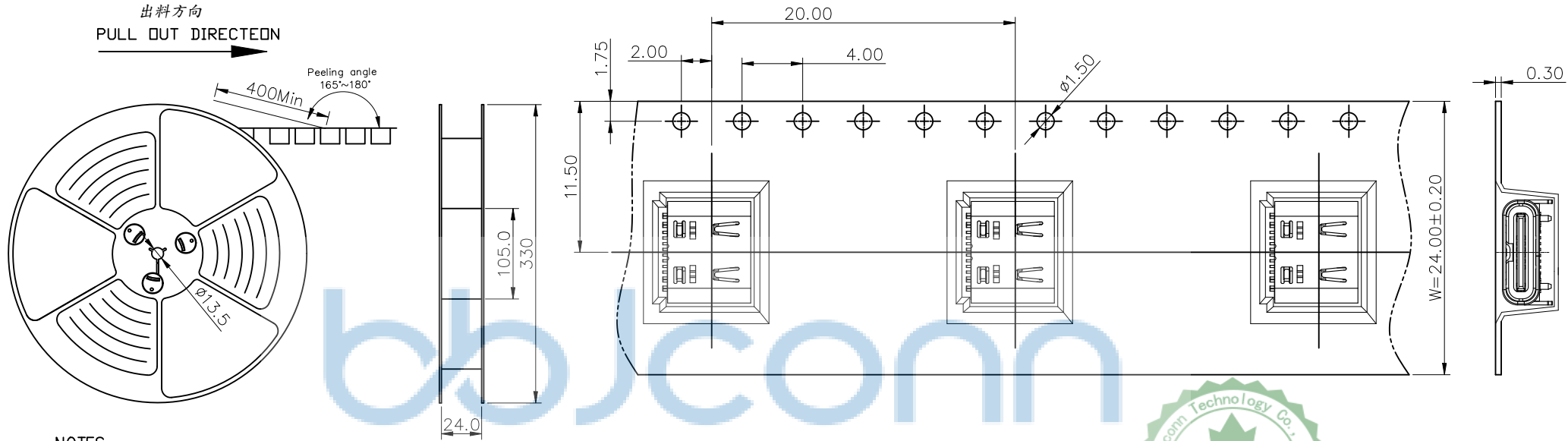
RECOMMEND P.C.B LAYOUT (COMPONENT SIDE)
TOLERANCE FOR PCB LAYOUT IS ± 0.05

USB TYPE-C PIN ASSIGNMENTS

PIN NUMBER	SIGNAL NAME	PIN NUMBER	SIGNAL NAME
A1	GND	B12	GND
A4	VBUS	B9	VBUS
A5	CC1	B8	SBU2
A6	Dp1	B7	Dn2
A7	Dn1	B6	Dp2
A8	SBU1	B5	CC2
A9	VBUS	B4	VBUS
A12	GND	B1	GND



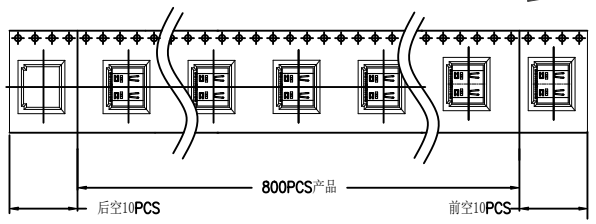
THIS DOCUMENT IS THE SOLE PROPERTY OF BBJconn Technology Co.,Ltd. Corporation AND SHOULD NOT BE USED IN WHOLE OR IN PART WITHOUT PRIOR WRITTEN PERMISSION.		深圳市步步精科技有限公司 .X: ± 0.38 X: $\pm 3^*$.XX: ± 0.25 .X: $\pm 2^*$.XXX: ± 0.13 .XX: $\pm 1^*$		NAME: TYPE-C 16P 母座 SMT 镀金30U 板上四脚插 带柱 外壳四脚点带弹不折弯凸包印子 L=7.35 CH=1.68 编带	
APPD.	JM_Zheng	P.J. NO.: 126-273-160001-V2G		SIZE: A4 DRW NO.:	
CHKD.	LYX	FINISH: SEE NOTES		MAT'L.: SEE NOTES	
PDWG.NO:	0100-2	DR.	TSP	SCALE: N/A	REV.: A0 UNIT: mm PAGE: 2/3



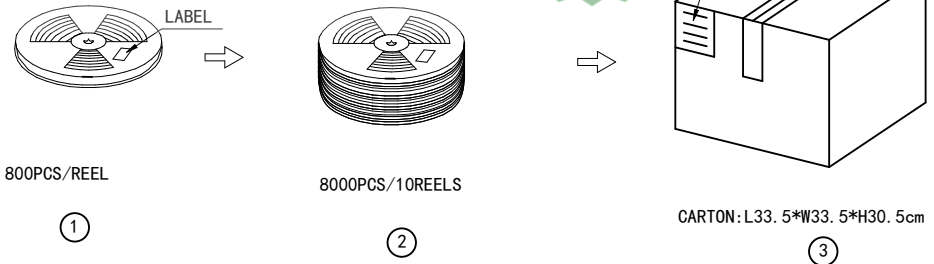
NOTES

1. 帶引導長度
LEAD TAPE LENGTH
出料方向
PULL OUT DIRECTEON

出料方向
PULL OUT DIRECTEON



2. 上帶 剝離力為：0.1~1.3N(10.2gf~130gf)
PEELING OFF FORCE OF TOP TAPE: 0.1~1.3N(10.2gf~130gf)
出貨運輸過程中一定注意：
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT：
卷帶在運輸過程中不能散開
PEELING OFF SHOULD NOT BE ALLOWED DURING TRANSPORTATION



產品料號 (Product No.)	包裝容量 (Packing Capacity)			重量 Weight (Kg)		
	pcs/reel	reels/Carton	Pcs/Carton	N. W. /Pcs	N. W. /reel	N. W. /Carton
	800	10	8000	----	----	----

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.X: ±0.38 X: ±3* .XX: ±0.25 .X: ±2* .XXX: ±0.13 .XX: ±1*		NAME: TYPE-C 16P 母座 SMT 鍍金30U 板上四脚插 帶柱 外壳四脚点带弹不折弯凸包印子 L=7.35 CH=1.68 編帶	
APPD. JM_Zheng	P.J. NO.: 126-273-160001-V2G		SIZE: A4 DRW NO.:
CHKD. LYX	FINISH: SEE NOTES		MAT'L.: SEE NOTES
DR. TSP	SCALE: N/A	REV.: A0	UNIT: mm PAGE: 3/3